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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Bandyopadhyay et al.

Attorney Docket No.:  
NOVLP088/NVLS-2882

Application No.: 10/825,888

Examiner: SMITH

Filed: April 16, 2004

Group: 2891

Title: METHOD TO IMPROVE MECHANICAL  
STRENGTH OF LOW-K DIELECTRIC FILM  
USING MODULATED UV EXPOSURE

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on November 13, 2006 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: \_\_\_\_\_

Tara Hayden

**INFORMATION DISCLOSURE STATEMENT  
BEFORE FINAL ACTION OR NOTICE OF ALLOWANCE  
(37 CFR §§ 1.56 AND 1.97(c))**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, a copy of which is attached, may be material to examination of the above-identified patent application. Applicants submit this reference in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that this reference indeed constitutes prior art.

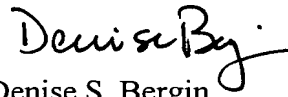
This Information Disclosure Statement is being filed after the mailing date of the first Office Action on the merits, or after three months of the filing date of this application, whichever event occurred last, but it is believed before the mailing date of either: (i) a final action under §1.113 or (ii) a notice of allowance under §1.311, whichever occurs first.

Accompanying this Information Disclosure Statement is

- ☐ a statement as specified in 37 CFR 1.97(e); or  
☒ the fee set forth in 37 CFR 1.17(p).

If fees are due, enclosed is our Check No. ~~12545~~ for \$180.00 in payment of the Information Disclosure Statement Fee. If it is determined that any additional fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP088).

Respectfully submitted,  
BEYER WEAVER & THOMAS, LLP



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<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No. NOVLP088/NVLS-2882	Application No.: 10/825,888
	Applicant: Bandyopadhyay et al. Filing Date April 16, 2004	Group 2891

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	2006/0197881	09.2006	Kang et al.			
	A2	6,331,480	12.2001	Tsai et al.			

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	U.S. Office Action mailed May 2, 2006, from U.S Application No. 10/295,965.
	C2	U.S. Office Action mailed August 9, 2005, from U.S Application No. 10/295,965.
	C3	U.S. Office Action mailed June 14, 2006, from U.S Application No. 10/789,103 [Atty Dkt No. NOVLP094/NVLS-2919].
	C4	U.S. Office Action mailed September 8, 2006, from U.S Application No. 10/404,693 [Atty Dkt No. NOVLP064/NVLS-794].
	C5	U.S. Office Action mailed September 7, 2006, from U.S Application No. 10/820,525 [Atty Dkt No. NOVLP091/NVLS-2889].
	C6	U.S. Office Action mailed July 12, 2006, from U.S Application No. 10/672,305 [Atty Dkt No. NOVLP069/NVLS-2821].
	C7	Wu et al., "Methods for Fabricating High Hardness/Modules Low Dielectric Constant Materials," Novellus Systems, Inc., Appln No. 11/369,658, filed March 6, 2006, pp. 1-33. [NOVLP148/NVLS-3111]
	C8	Dhas et al., "Method of Reducing Defects in PECVD TEOS Films," Novellus Systems, Inc., Appln No. 11/396,303, filed March 30, 2006, pp. 1-21. [NOVLP160/NVLS-3168]
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.